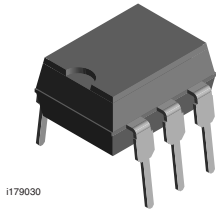
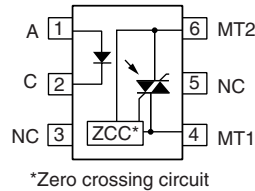


Phototriac, Zero Crossing, 1.5 kV/ μ s dV/dt, 600 V



H179030


FEATURES

- 1500 V/ μ s dV/dt minimum
- 600 V blocking voltage
- 100 mA on-state current
- Zero crossing detector
- Low input trigger current
- 6 pin DIP package
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC


RoHS
COMPLIANT

APPLICATIONS

- Household appliances
- Triac drive/AC motor drives
- Solenoid/valve controls
- Office automation equipment/machine
- Temperature (HVAC)/lighting controls
- Switching power supply

AGENCY APPROVALS

- UL1577, file no. E52744 system code U/J
- CUL - file no. E52744, equivalent to CSA bulletin 5A
- DIN EN 60747-5-5 (VDE 0884) available with option 1
- BSI IEC 60950

DESCRIPTION

The VO3062/3063 triac driver family consists of a GaAs infrared LED optically coupled to a monolithic photosensitive zero crossing triac detector chip.

The 600 V blocking voltage permits control of off-line voltages up to 240 VAC, with a safety factor of more than two, and is sufficient for as much as 380 V.

| ORDER INFORMATION | |
|-------------------|--|
| PART | REMARKS |
| VO3063 | DIP-6, ZC, 600 V, $I_{ft} = 5$ mA |
| VO3062 | DIP-6, ZC, 600 V, $I_{ft} = 10$ mA |
| VO3063-X006 | DIP-6 400 mil, ZC, 600 V, $I_{ft} = 5$ mA |
| VO3062-X006 | DIP-6 400 mil, ZC, 600 V, $I_{ft} = 10$ mA |
| VO3063-X007T | SMD-6, ZC, 600 V, $I_{ft} = 5$ mA |
| VO3062-X007T | SMD-6, ZC, 600 V, $I_{ft} = 10$ mA |

Note

For additional information on the available options refer to option information.

| ABSOLUTE MAXIMUM RATINGS | | | | | |
|-----------------------------------|----------------------|-------------|--------------|-------|------|
| PARAMETER | TEST CONDITION | PART | SYMBOL | VALUE | UNIT |
| INPUT | | | | | |
| Reverse voltage | | | V_R | 6 | V |
| Forward current - continuous | | | I_F | 60 | mA |
| Power dissipation | | | P_{diss} | 100 | mW |
| OUTPUT | | | | | |
| Off state output terminal voltage | | VO3062/3063 | V_{DRM} | 600 | V |
| Peak repetitive surge current | PW = 100 ms, 120 pps | | I_{TSM} | 1 | A |
| Power dissipation | | | P_{diss} | 200 | mW |
| On-state RMS current | | | $I_{T(RMS)}$ | 100 | mA |

| ABSOLUTE MAXIMUM RATINGS | | | | | |
|-----------------------------|----------------|------|------------------|---------------|------------------|
| PARAMETER | TEST CONDITION | PART | SYMBOL | VALUE | UNIT |
| COUPLER | | | | | |
| Isolation test voltage | t = 1 s | | V _{ISO} | 5300 | V _{RMS} |
| Total power dissipation | | | P _{tot} | 300 | mW |
| Operating temperature range | | | T _{amb} | - 40 to + 100 | °C |
| Storage temperature range | | | T _{stg} | - 55 to + 150 | °C |
| Soldering temperature | maximum ≤ 10 s | | T _{sld} | 260 | °C |

Note

T_{amb} = 25 °C, unless otherwise specified.

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

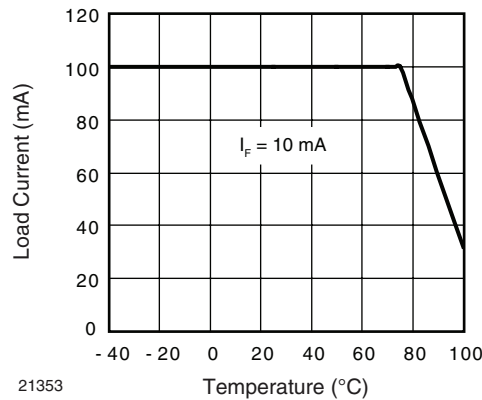


Fig. 1 - On-State Current (RMS) vs. Temperature

Note

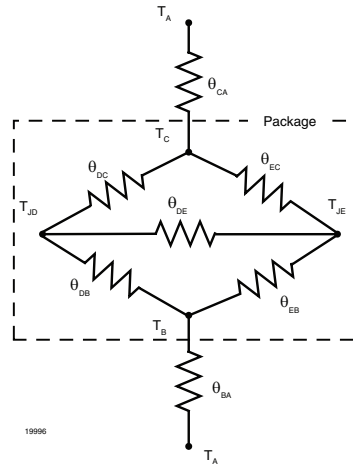
The allowable load current was calculated out under a given operating conditions and only for reference:

LED power: Q_E = 0.015 W, R_{BA} (2-layer) = 72 °C/W

| THERMAL CHARACTERISTICS | | | | |
|---|----------------|-------------------|-------|------|
| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
| Maximum LED junction temperature | | T _{Jmax} | 125 | °C |
| Maximum output die junction temperature | | T _{Jmax} | 125 | °C |
| Thermal resistance, junction emitter to board | | θ _{JEB} | 150 | °C/W |
| Thermal resistance, junction emitter to case | | θ _{JEC} | 139 | °C/W |
| Thermal resistance, junction detector to board | | θ _{JDB} | 78 | °C/W |
| Thermal resistance, junction detector to case | | θ _{JDC} | 103 | °C/W |
| Thermal resistance, junction emitter to junction detector | | θ _{JED} | 496 | °C/W |
| Thermal resistance, case to ambient | | θ _{CA} | 3563 | °C/W |

Note

The thermal model is represented in the thermal network below. Each resistance value given in this model can be used to calculate the temperatures at each node for a given operating condition. The thermal resistance from board to ambient will be dependent on the type of PCB, layout and thickness of copper traces. For a detailed explanation of the thermal model, please reference Vishay's Thermal Characteristics of Optocouplers Application note.



| ELECTRICAL CHARACTERISTICS | | | | | | | |
|--|--|--------|------------|------|------|------|---------------|
| PARAMETER | TEST CONDITION | PART | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| INPUT | | | | | | | |
| Reverse current | $V_R = 6\text{ V}$ | | I_R | | | 10 | μA |
| Forward voltage | $I_F = 30\text{ mA}$ | | V_F | | 1.2 | 1.5 | V |
| OUTPUT | | | | | | | |
| Leakage with LED off, either direction | $V_{DRM} = 600\text{ V}$ | | I_{DRM} | | 10 | 500 | nA |
| Critical rate of rise off-state voltage | $V_D = 400\text{ V}$ | | dV/dt | 1500 | 2000 | | V/ μ s |
| COUPLER | | | | | | | |
| LED trigger current, current required to latch output | | VO3063 | I_{FT} | | | 5 | mA |
| | | VO3062 | I_{FT} | | | 10 | mA |
| Peak on-state voltage, either direction | $I_{TM} = 100\text{ mA Peak}$ $I_F = \text{Rated } I_{FT}$ | | V_{TM} | | 1.7 | 3 | V |
| Holding current, either direction | | | I_H | | 200 | | μA |
| Inhibit voltage (MT1-MT2 voltage above which device will not trigger) | | | V_{INH} | | 12 | 22 | V |
| Leakage in inhibited state | $I_F = 10\text{ mA maximum}$, at rated V_{DRM} , off state | | V_{DRM2} | | 250 | 1000 | μA |

Note

$T_{amb} = 25\text{ }^\circ\text{C}$, unless otherwise specified.

Minimum and maximum values were tested requirements. Typical values are characteristics of the device and are the result of engineering evaluations. Typical values are for information only and are not part of the testing requirements.

| SAFETY AND INSULATION RATINGS | | | | | | | |
|--|-------------------------|------------|------|----------|----------------|------------|--|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT | |
| Climatic classification | IEC 68 part 1 | | | 40/85/21 | | | |
| Pollution degree | DIN VDE 0109 | | | 2 | | | |
| Comparative tracking index per DIN IEC 112/VDE 0303 part 1, group IIIa per DIN VDE 6110 175 399 | | CTI | 175 | | | | |
| Highest allowable overvoltage | Transient overvoltage | V_{IOTM} | 8000 | | | V_{peak} | |
| Maximum working insulation voltage | Recurring peak voltage | V_{IORM} | 890 | | | V_{peak} | |
| Insulation resistance at 25 $^\circ\text{C}$ | $V_{IO} = 500\text{ V}$ | R_{IS} | | | $\geq 10^{12}$ | Ω | |
| Insulation resistance at T_S | $V_{IO} = 500\text{ V}$ | R_{IS} | | | $\geq 10^9$ | Ω | |
| Insulation resistance at 100 $^\circ\text{C}$ | $V_{IO} = 500\text{ V}$ | R_{IS} | | | $\geq 10^{11}$ | Ω | |

| SAFETY AND INSULATION RATINGS | | | | | | |
|---|--|----------|------|------|------|------------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Partial discharge test voltage | Method a, $V_{pd} = V_{IORM} \times 1.875$ | V_{pd} | | | 1325 | V_{peak} |
| Safety limiting values - maximum values allowed in the event of a failure | Safety power rating | P_{SO} | | | 400 | mW |
| | Safety current rating | I_{SI} | | | 150 | mA |
| | Safety temperature rating | T_{SI} | | | 165 | °C |
| Minimum external air gap (clearance) | Measured from input terminals to output terminals, shortest distance through air | | ≥ 7 | | | mm |
| Minimum external tracking (creepage) | Measured from input terminals to output terminals, shortest distance path along body | | ≥ 7 | | | mm |

Note

As per IEC 60747-5-2, 7.4.3.8.1, this optocoupler is suitable for “safe electrical insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits.

TYPICAL CHARACTERISTICS

$T_{amb} = 25\text{ °C}$, unless otherwise specified

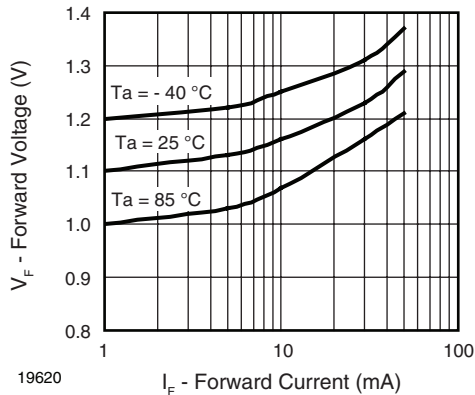


Fig. 2 - Forward Voltage vs. Forward Current

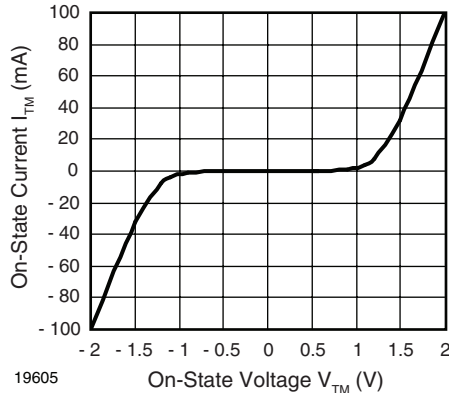


Fig. 4 - On-State Current vs. V_{TM}

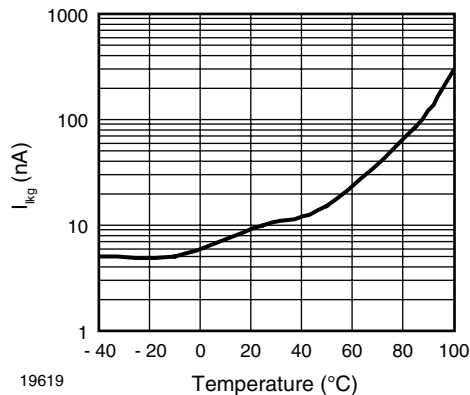


Fig. 3 - Off-State Leakage Current vs. Temperature

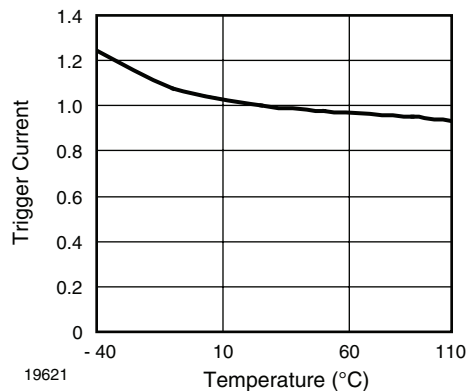


Fig. 5 - Normalized Trigger Current vs. Temperature

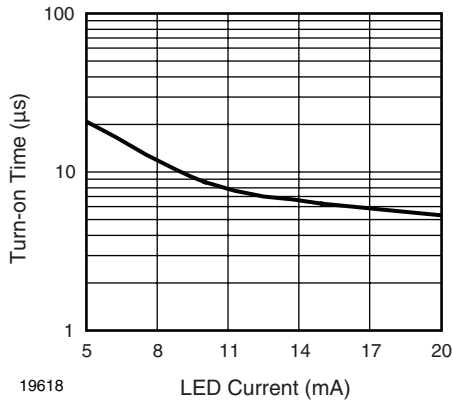


Fig. 6 - Turn-on Time vs. LED Current

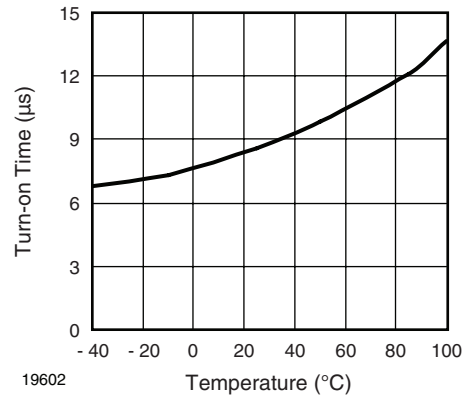


Fig. 8 - Turn-on Time vs. Temperature

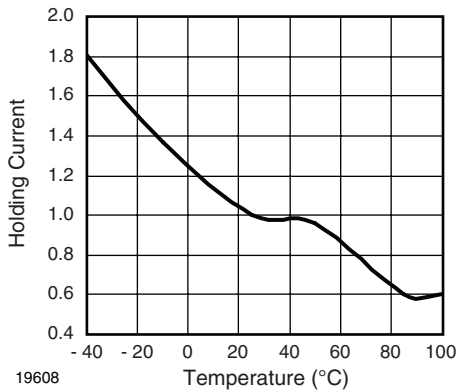


Fig. 7 - Normalized Holding Current vs. Temperature

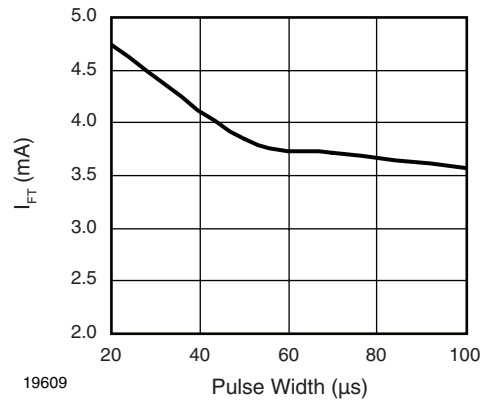
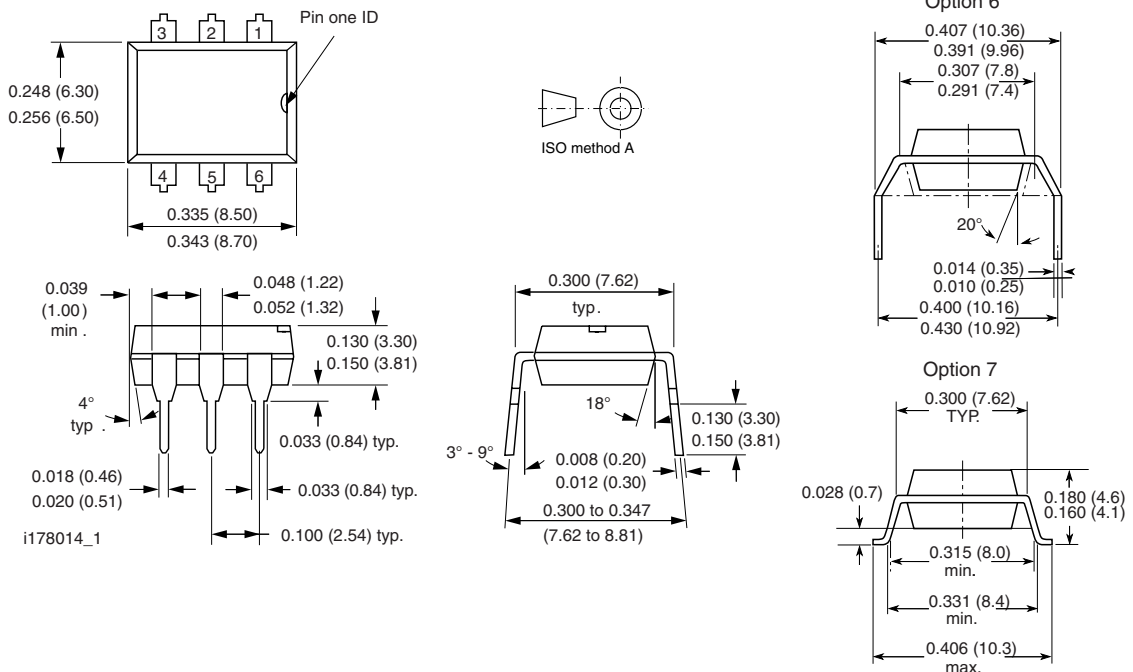


Fig. 9 - Trigger Current vs. Pulse Width

PACKAGE DIMENSIONS in inches (millimeters)




OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
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Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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- Комплексную поставку.
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- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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